

STM32WL_QFN48_HP_DirectTie_RefBoard

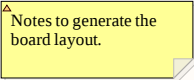
MB1789_HP

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- Sheet 1: Project overview (this page)
- Sheet 2: MB1789_HP.SchDoc

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.



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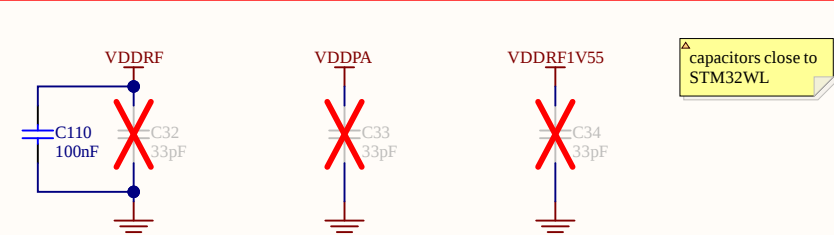
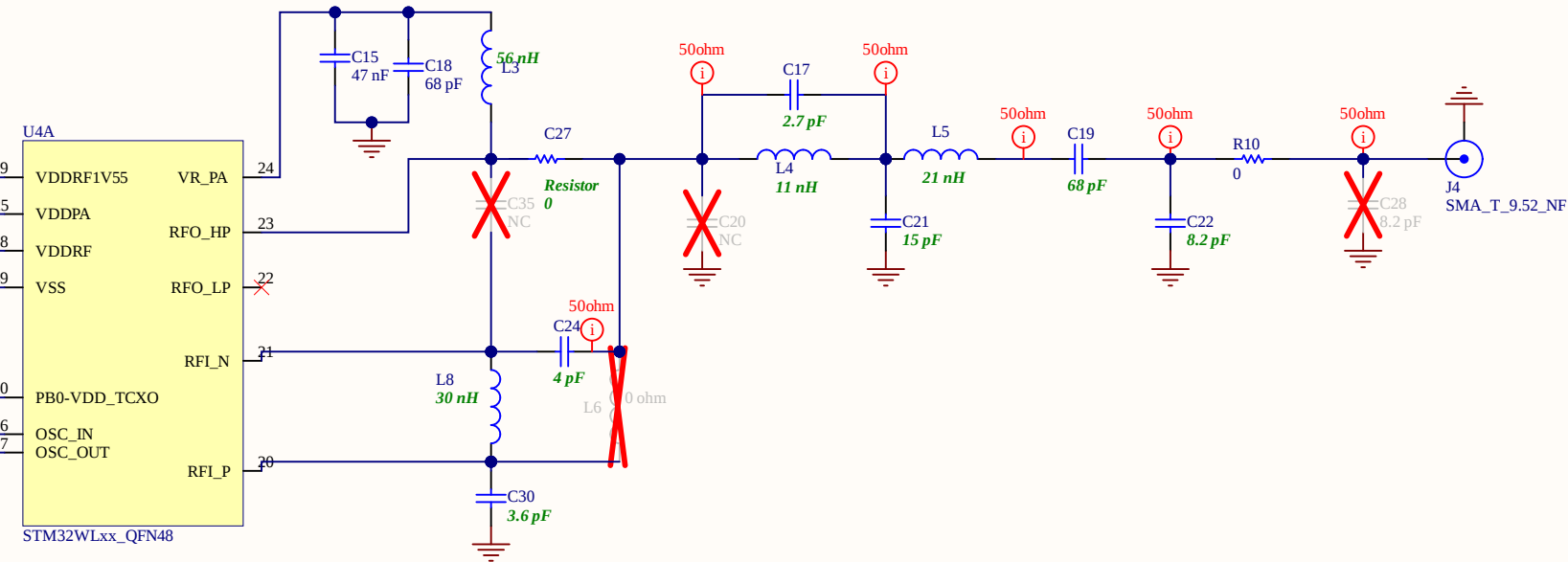
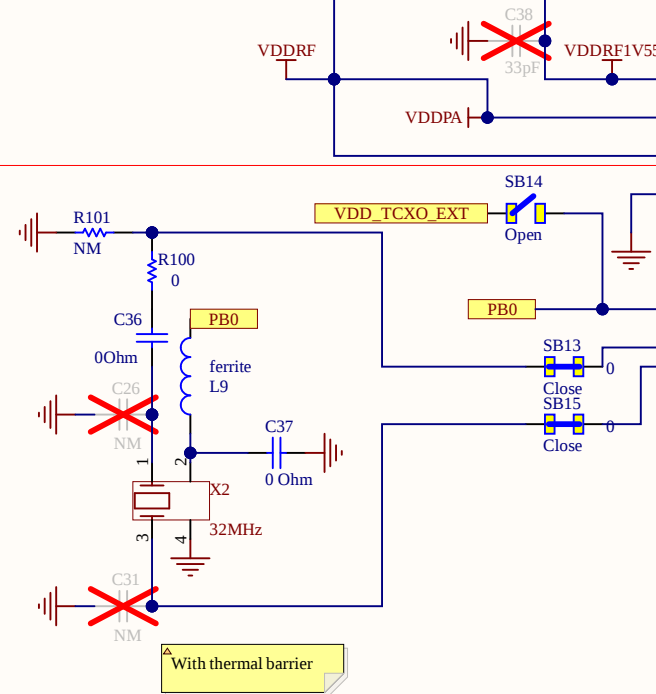
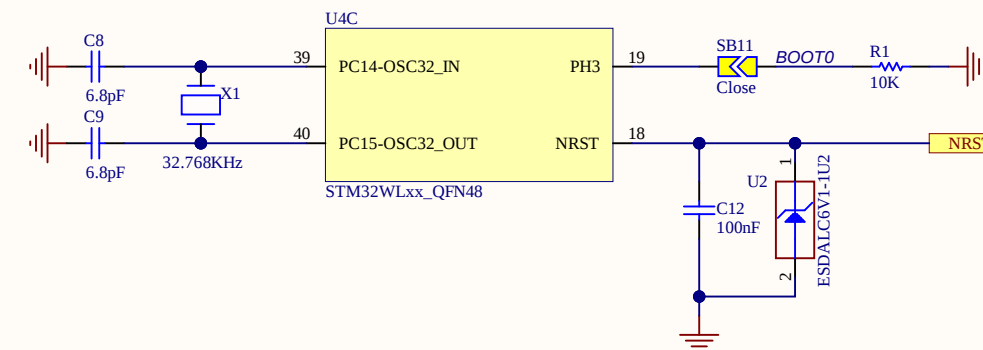
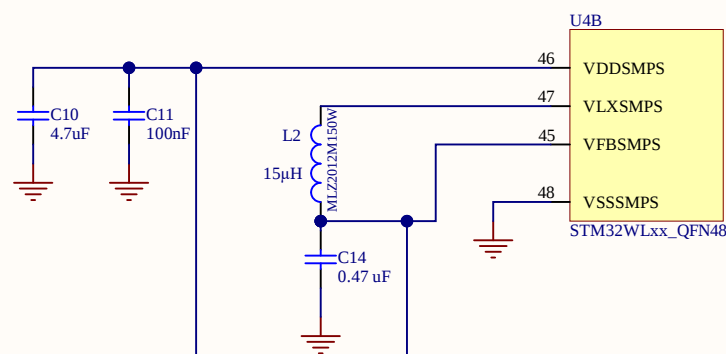
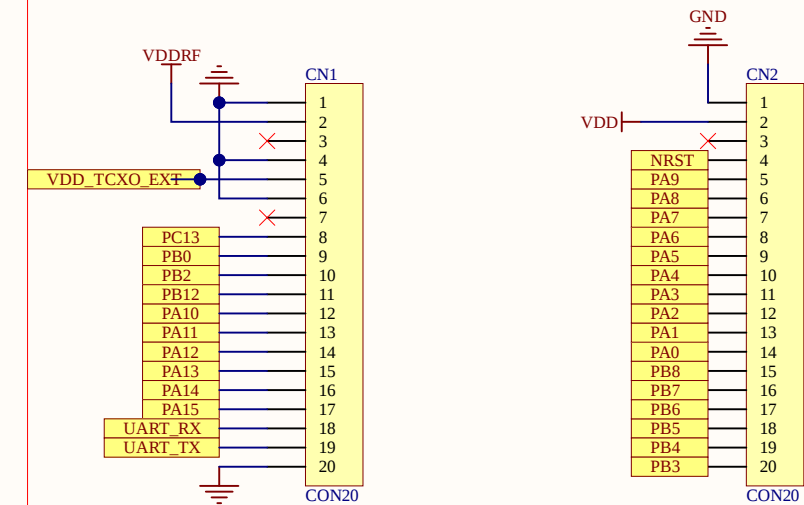
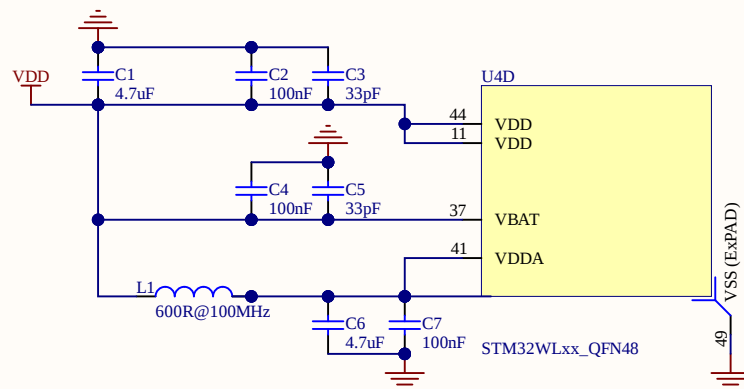
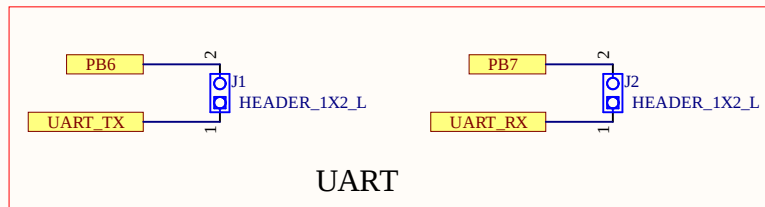
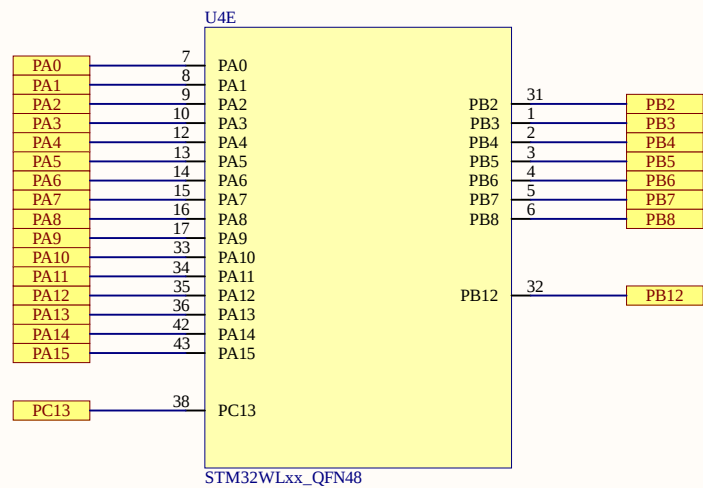
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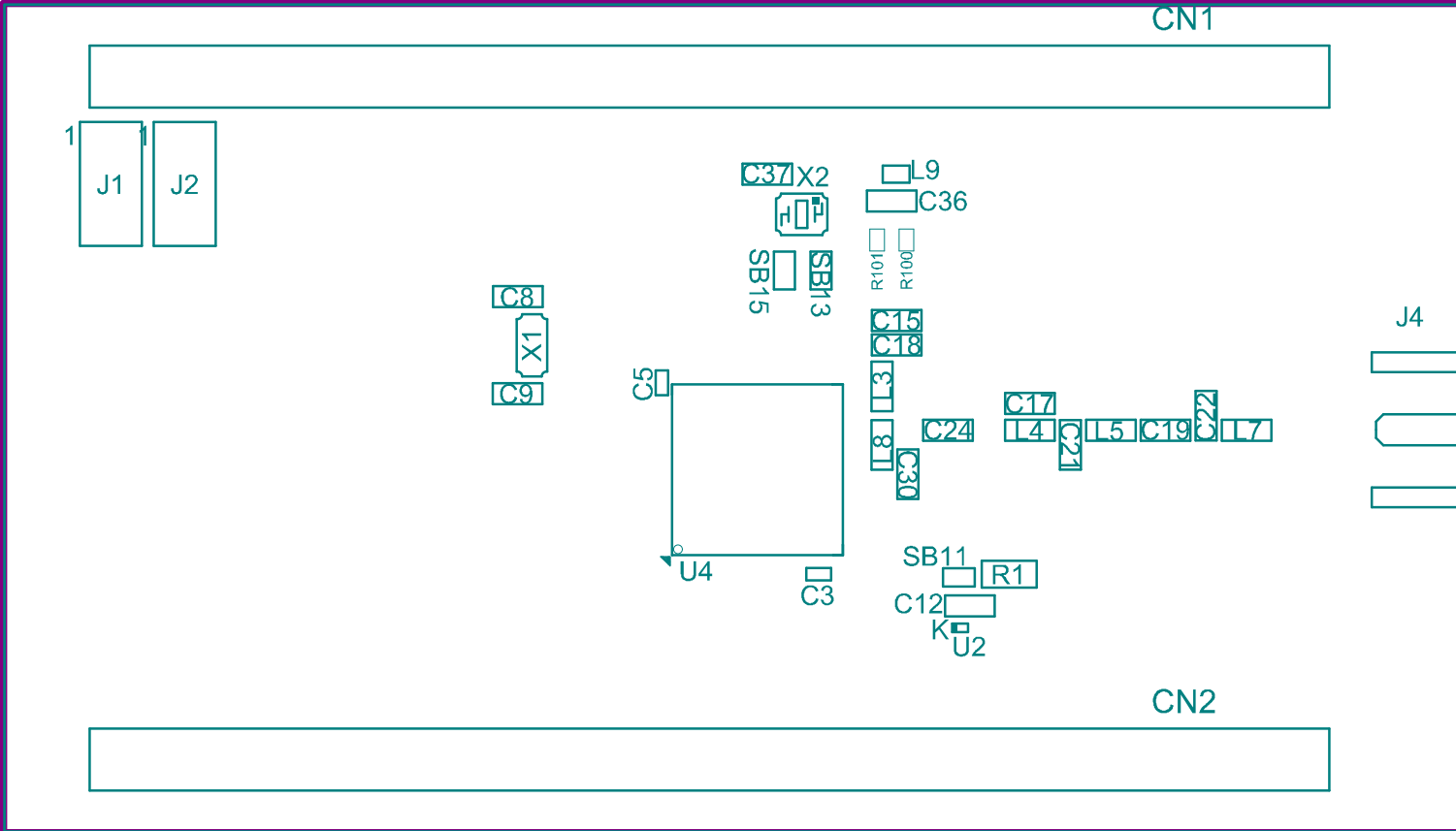
U_Top
MB1789_HP.SchDoc



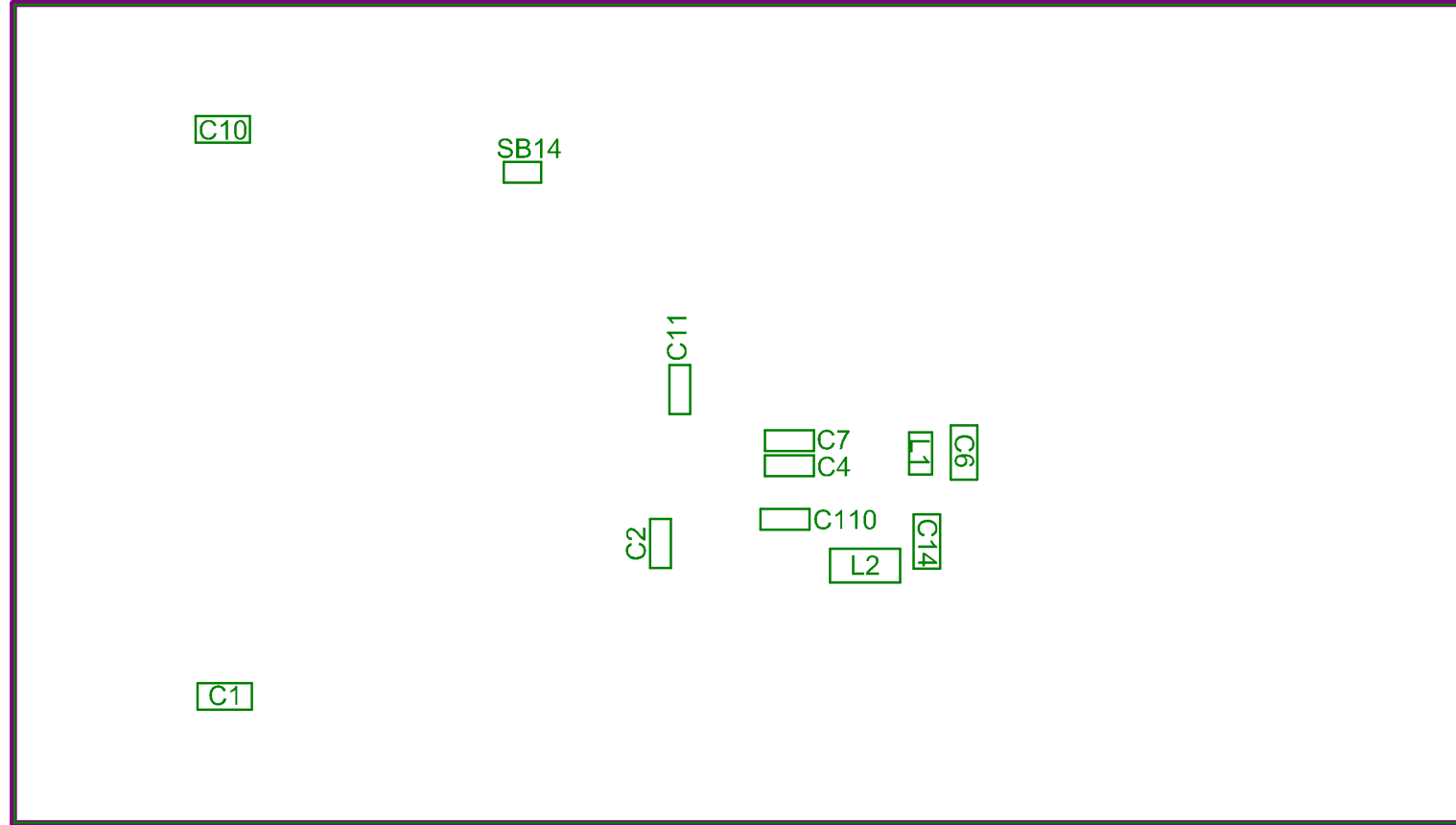
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Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Variant: LowBand_HighPower		
Revision: A-01		Reference: MB1789_HP
Size: A4	Date: 04-04-2022	Sheet: 1 of 2



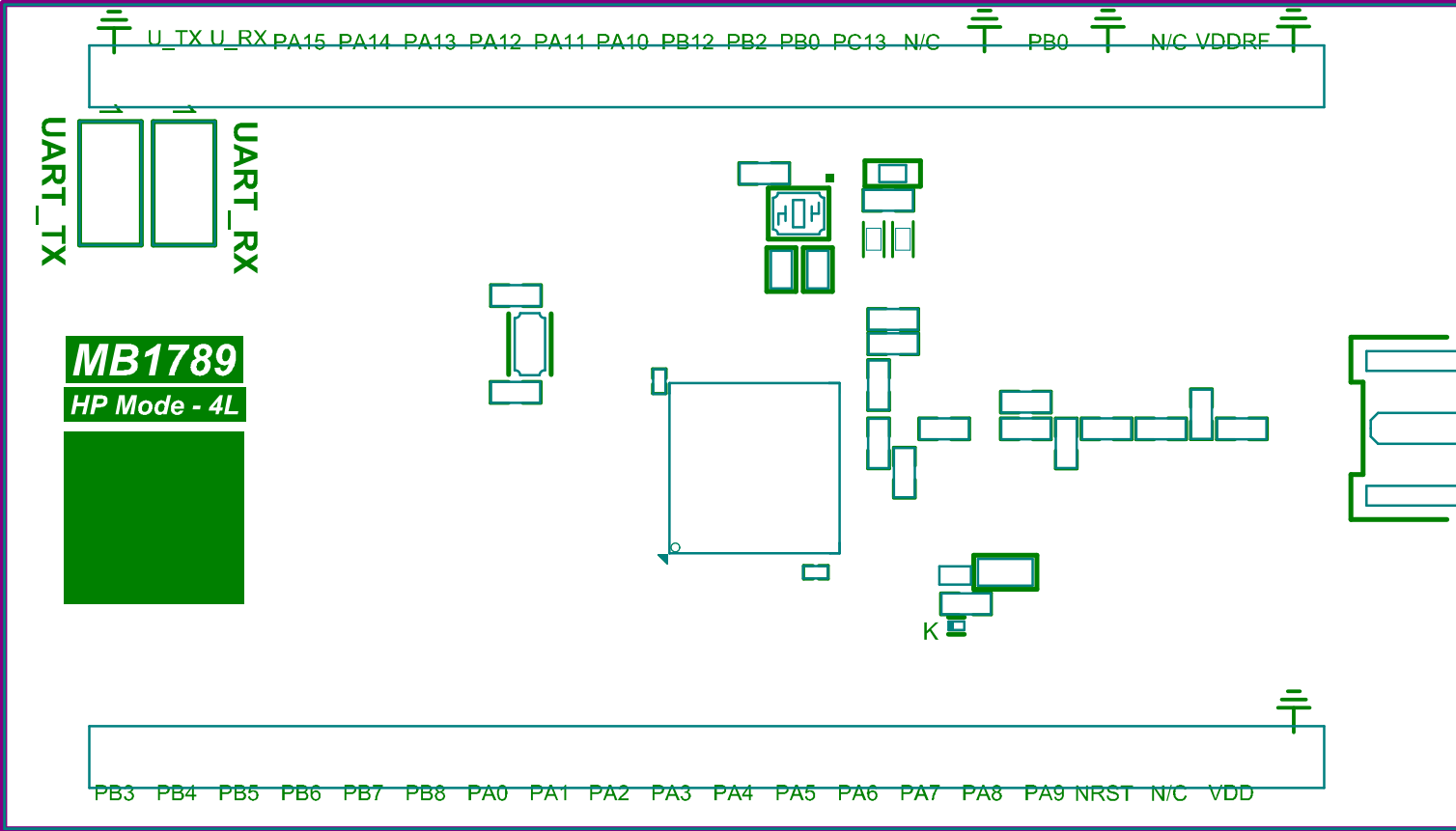




Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Top Assembly	Gerber: .GM14	
Variant: LowBand_HighPower	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	

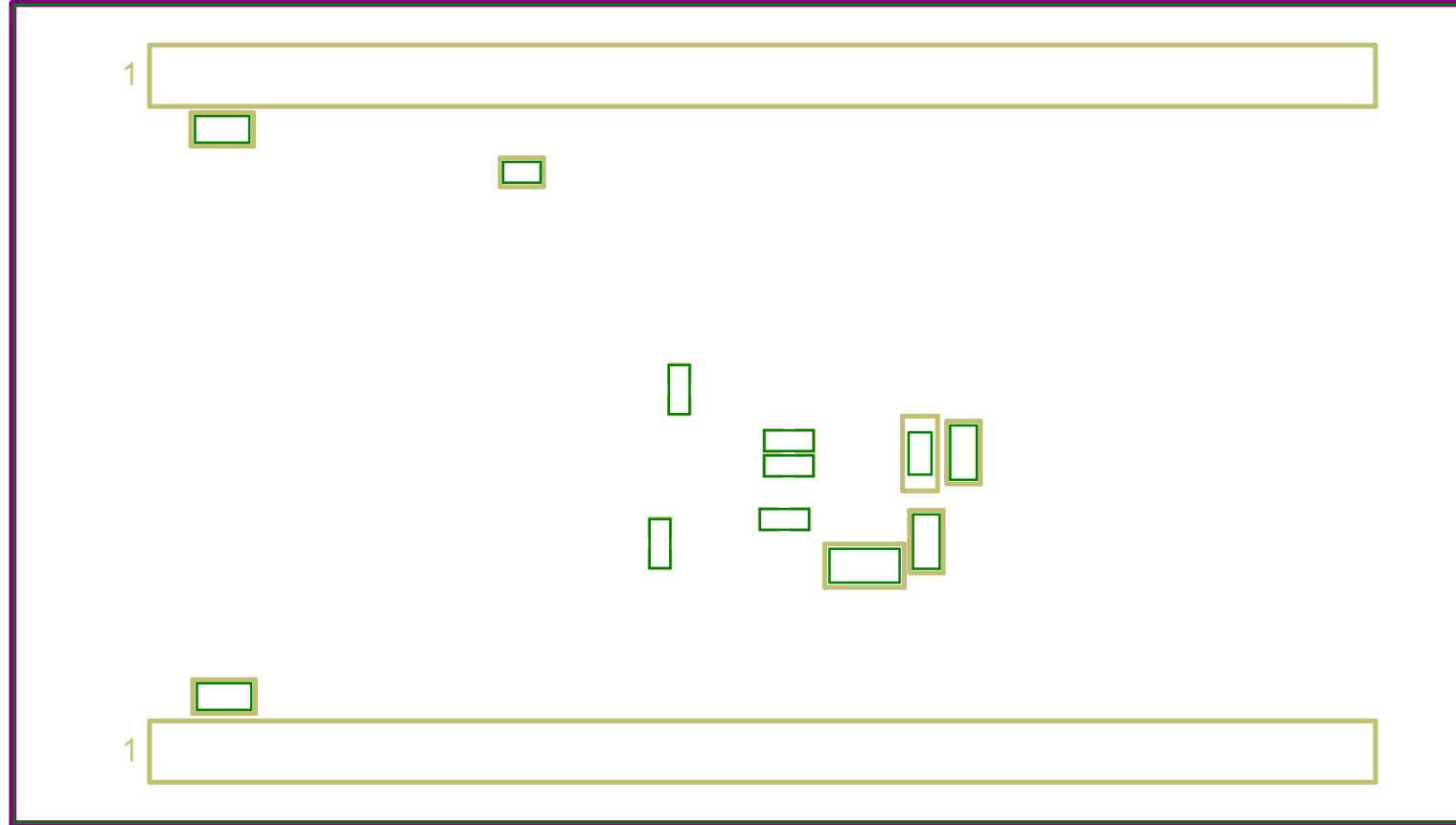


Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Bottom Assembly	Gerber: .GM15	
Variant: LowBand_HighPower	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	



Top Overlay

.GTO



Bottom Overlay

.GBO